

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
PING-YIN LIU	09/09/2013
YEUR-LUEN TU	09/09/2013
CHIA-SHIUNG TSAI	09/09/2013
XIAOMENG CHEN	09/09/2013
PIN-NAN TSENG	09/18/2013
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	NO. 8, LI-HSIN RD. 6
<b>Internal Address:</b>	SCIENCE-BASED INDUSTRIAL PARK
<b>City:</b>	HSIN-CHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17347001
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP (24061) IP SECTION
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<b>ATTORNEY DOCKET NUMBER:</b>	2013-0604/24061.2580US04
<b>NAME OF SUBMITTER:</b>	MARCY OGADO
<b>SIGNATURE:</b>	/Marcy Ogado/
<b>DATE SIGNED:</b>	06/16/2021

**Total Attachments: 3**

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## ASSIGNMENT

WHEREAS, we,

- |     |                  |    |   |
|-----|------------------|----|---|
| (1) | Ping-Yin Liu     | of | 3F, No. 7, Bao-an Road<br>Yonghe City, Taipei County 234<br>Taiwan, R.O.C.  |
| (2) | Yeur-Luen Tu     | of | No. 3-6, Lane 12, Gong-Xue Road<br>Taichung, Taiwan, R.O.C                  |
| (3) | Chia-Shiung Tsai | of | No. 5, 50 Alley, 62 Lane<br>Gua-Tsuey Road<br>Hsin-Chu, Taiwan, R.O.C.      |
| (4) | Xiaomeng Chen    | of | No. 5, Lane 37, ZhuAn 2nd Road<br>Baoshan County, Hsinchu<br>Taiwan, R.O.C. |
| (5) | Pin-Nan Tseng    | of | No. 4, Alley 71, Tung-Feng Road<br>Hsiung-Shan, Hsin-Chu, Taiwan, R.O.C.    |

have invented certain improvements in

### DUAL FACING BSI IMAGE SENSORS WITH WAFER LEVEL STACKING

for which we have executed an application for Letters Patent of the United States of America,

  X   of even date filed herewith; and  
           filed on            and assigned application number           ; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize

and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ping-Yin Liu

Residence Address: 3F, No. 7, Bao-an Road  
Yonghe City, Taipei County 234 Taiwan, R.O.C.

Dated: ✓

Ping-Yin Liu  
Sep. 09, 2013.

✓

Sep. 09, 2013.  
Inventor Signature

Ping-Yin Liu

Inventor Name: Yeur-Luen Tu

Residence Address: No. 3-6, Lane 12, Gong-Xue Road, Taichung, Taiwan, R.O.C

Dated: ✓

Yeur-Luen Tu  
Sept. 09, 2013

✓

Yeur-Luen Tu  
Inventor Signature

Yeur-Luen Tu

Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road, Hsin-Chu, Taiwan, R.O.C.

Dated: ✓

09/09/2013

✓

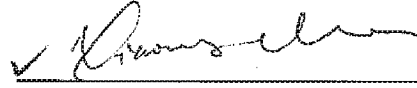
Chia-Shiung Tsai  
Inventor Signature

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Inventor Name: Xiaomeng Chen

Residence Address: No. 5, Lane 37, ZhuAn 2nd Road  
Baoshan County, Hsinchu Taiwan, R.O.C.

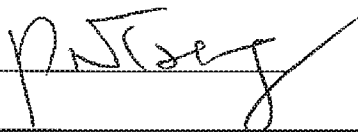
✓ Dated: 9/09/2013

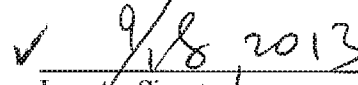
✓   
Inventor Signature

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Inventor Name: Pin-Nan Tseng

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Hsin-Chu, Taiwan, R.O.C.

✓ Dated: 

✓   
Inventor Signature